

IPC-HDBK-9798

Handbook for Press-fit Standard for Automotive Requirements and other High-Reliability Applications

Developed by the Cold Joining Press-fit Handbook Task Group (5-21n) of the Assembly & Joining Committee (5-20) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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Table of Contents

1 SCOPE		6.2.2 Packaging for Mass Production		
1.1	Applicability1	6.2.3 Final	Packaging for Shipping and Storage	16
1.2	Measurement Units	6.2.4 Product Storage (Warehouse)		
1.2.1	Verification of Dimensions	6.2.5 Packaging for Lab, Validation and		
1.3	Use of "Lead"	Retai	ned Samples	17
1.4	Abbreviations and Acronyms	7 TEST MI	ETHODS	17
1.5	Terms and Definitions	7.1 Stora	ge and Test Conditions	17
2 AF	PPLICABLE DOCUMENTS 1	7.2 Contact Resistance		17
2.1	IPC Documents	7.2.1 Test I	Equipment	17
2.2	International Electrotechnical	7.2.2 Test Procedure		17
	Commission Documents	7.3 Sprin	g Force Measurement	19
2.3	American Society for Testing and Materials 2	7.3.1 Defin	nition	19
3 IN	TRODUCTION TO PRESS-FIT TECHNOLOGY 2	7.3.2 Measurement Process		20
3.1	Background of Press-fit Technology 2	7.4 Push-	In Method and Typical Push-In Forces	21
3.2	Press-Fit Technology	7.4.1 Push	-In Method	21
3.3	Advantages and Challenges	7.4.2 Typic	cal Push-In Forces	22
3.4	Current and Future Trends	8 REWORK AND REPAIR		
4 CONTACT PHYSICS		BIBLIOGRAPHY		23
5 M	ATERIALS 6	APPENDIX	A Abbreviations and Acronyms	25
5.1	Pin Base Metal and Metallurgical Requirements 6		Figures	
5.1.1	Formability and Weldability 6	Figure 3-1	Compliant Press-Fit Zone in PPTH	2
5.1.2	Electrical Conductivity	Figure 3-2	Examples of Different Styles of Complian	
5.1.3	Yield Strength		Press-Fit Zones [1]	2
5.1.4	Resistance to Thermal Stress Relaxation	Figure 4-1	Current Flow Through the A-Spots	4
	Resistance Against Vibrations	Figure 5-1	Silicides in C70250 Alloy Visible as Blac Spots	
	Surface Requirements. 9	Figure 5-2	Thermal Relaxation Diagram	7
5.2	Surface Finish9	Figure 5-3	Conductivity vs. Strength Diagram of Copper Alloys	9
	Coating – Press-Fit Surface Finishes 9	Figure 5-4	Schematic View of a Longitudinal	
5.2.2	Functional Impact of Surface Finishes	Cross-Section Indicating the Loca for the Measurements (A to F) Sh	Cross-Section Indicating the Locations	
5.3	Printed Boards		for the Measurements (A to F) Shown as a Example on a Four-Layer PB	
	Copper Thickness	Figure 5-5	Schematic View of Biasing Press-Fit	
	Printed Board Surface Finishes	1 iguie 5 5	Applications Between e.g., Two Complian Press-Fit Zones	
5.3.4	Dimensioning	Figure 6-1	Front and Side Views of Fixture (1) and Support Plate (2) for Push-In Process	14
	ANDLING AND PACKAGING	Figure 6-2	Fixture (1) and Push-Out Tool (2) for Push-Out Process	
6.1	General 14	Figure 6-3	Strip with and without Overmolding	
6.2	Handling of Compliant Press-Fit Products	Figure 6-4	Reel Packaging	
o.2.1	Handling for Testing and Qualification14	Figure 6-5	Single Parts	

IPC-HDBK-9798 April 2022

Figure 6-6	Blister Packaging	15		Tables
Figure 6-7	Tube Packaging	16	Table 3-1	Advantages and Common Challenges of
Figure 6-8	Tray Packaging.	16		Press-Fit Technology with Reference to Selective Soldering
Figure 7-1	Contact Resistance Measurement Schematic	17	Table 4-1	Mechanical and Electrical Tests in IPC-9797
Figure 7-2	Using an Adjacent PPTH for Contacting	17	T 11 40	
Figure 7-3	Using an Adjacent Via for Contacting	18	Table 4-2	Optical and Cross-Sectional Inspections in IPC-9797
Figure 7-4	Using Adjacent Vias for Contacting in a Daisy Chain.	18	Table 4-3	Requirements for PB, Compliant Press-Fit Zone and Related Tests in IPC-9797 6
Figure 7-5	Using the PPTH for Contacting in a Daisy Chain	18	Table 5-1	Typically Applied Copper Alloys for Press-Fit Connectors and Their Properties 8
Figure 7-6	Principle of the Spring Force Measurement (SFM) of Compliant Press-Fit Zones	19	Table 5-2	Example for a Typically Observed PPTH Definition
Figure 7-7	Typical Spring-Force Measurement Characteristics (the corrective curve needs to be subtracted from the measured curves for the complete measurement)	19	Table 6-1	Packaging Levels
Figure 7-8	Schematic of Spring Force Measurement Tool	20		
Figure 7-9	Example for the Spring Force Measurement Preparation of a Triple Pin			
Figure 7-10	Slow Speed Push-In Equipment (A) and a Typical Push-In Force Curve (B)	21		
Figure 7-11	High Speed Push-In Equipment (A) and a Typical Push-In Force Curve (B)	22		
Figure 7-12	Different PB Surface Finishes (push-in force vs depth)	22		
Figure 7-13	Push-In Forces for Different Press-Fit Designs.	. 23		
Figure 7-14	Push-In Forces: Various Plating Options on the Same Pin with the Same PB Finish.	23		

April 2022 IPC-HDBK-9798

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1 SCOPE

This document provides guidelines and supporting information for manufacturing electronic assemblies using compliant press-fit technology. The intent is to explain the "how-to" and "why" information, and fundamentals for these processes.

Additional detailed information can be found in documents referenced within each individual section. Users are encouraged to use those referenced documents to better understand the applicable subject areas.

This handbook is supporting the IPC-9797 standard.

- **1.1 Applicability** This handbook is for guidance only. The design concepts, guidelines, and procedures presented in this document are not requirements, and this document is not binding, unless separately and specifically included by the applicable contract, approved drawing(s), or purchase order.
- **1.2 Measurement Units** This standard uses International System of Units (SI units) per ASTM SI10, IEEE/ASTM SI 10, Section 3 [Imperial English equivalent units are in brackets for convenience]. The SI units used in this standard are millimeters (mm) [in] for dimensions and dimensional tolerances, Celsius (°C) [°F] for temperature and temperature tolerances, grams (g) [oz] for weight, and lux (lx) [footcandles] for illuminance.

Note: This standard uses other SI prefixes (ASTM SI10, Section 3.2) to eliminate leading zeros (for example, 0.0012 mm becomes $1.2 \mu m$) or as an alternative to powers-of-ten ($3.6 \times 10^3 \text{ mm}$ becomes 3.6 m).

- **1.2.1 Verification of Dimensions** When an inspection is done on an assembly, measuring dimensions and determining percentages listed in the standard are not required unless there is a doubt or a question is raised about the acceptance of the product. When there is a doubt or a question is raised, then a referee determination should be implemented, at which time measurements should be made or percentages calculated using the referee magnifications defined in the standard. For determining conformance to the specifications in this standard, round all observed or calculated values "to the nearest unit" in the last right-hand digit used in expressing the specification limit, in accordance with the rounding method of ASTM Practice E29. For example, specifications of 2.5 mm max, 2.50 mm max, or 2.500 mm max, round the measured value to the nearest 0.1 mm, 0.01 mm, or 0.001 mm, respectively, and then compare to the specification number cited.
- **1.3 Use of "Lead"** For readability and translation, this document uses the noun "lead" only to describe leads of a component. The metallic element "lead" is always written as Pb.
- **1.4 Abbreviations and Acronyms** Periodic table elements are abbreviated in the standard. See Appendix A for abbreviations, including elements and acronyms used in this standard.
- **1.5 Terms and Definitions** Other than those terms listed in IPC-9797, the definitions of terms used in this handbook are in accordance with IPC-T-50.

2 APPLICABLE DOCUMENTS

2.1 IPC Documents¹

IPC-T-50 Terms and Definitions for Interconnecting and Packaging Electronic Circuits

IPC-6012 Qualification and Performance Specification for Rigid Printed Boards

IPC-6012EA Automotive Applications Addendum to IPC-6012E, Qualification and Performance Specification for Rigid Printed Boards

IPC-9797 Press-fit Standard for Automotive Requirements and other High-Reliability Applications

IPC-A-600 Acceptability of Printed Boards

IPC-4552 Specification for Electroless Nickel/Immersion Gold (ENIG) Plating for Printed Boards

IPC-4553 Specification for Immersion Silver Plating for Printed Boards

¹ www.ipc.org

² www.iec.ch

³ www.astm.org

IPC-HDBK-9798 April 2022

IPC-4554 Specification for Immersion Tin Plating for Printed Circuit Boards

IPC-1602 Standard for Printed Board Handling and Storage

IPC-TM-650 Test Methods Manual

2.6.25 Conductive Anodic Filament (CAF) Resistance Test: X-Y Axis

2.2 International Electrotechnical Commission Documents²

IEC 60512-2-1 Connectors for electronic equipment – Tests and measurements – Part 2-1: Electrical continuity and contact resistance tests – Test 2a: Contact resistance – Millivolt level method

IEC 60068-1 Environmental testing – Part 1: General and guidance

IEC 60352-5 Solderless connections – Part 5: Press-in connections – General requirements, test methods and practical guidance

IEC 60721-3-1 Classification of environmental conditions – Part 3-1: Classification of groups of environmental parameters and their severities – Storage

Future IEC/TR 60068-3-82 (to be published 2022) Environmental Testing – Part 3-82: Supporting documentation and guidance – confirmation of the performance of whisker test method

2.3 American Society for Testing and Materials³

ASTM E29 Standard Practice for Using Significant Digits in Test Data to Determine Conformance with Specifications **ASTM SI10**, **IEEE/ASTM SI 10** American National Standard for Metric Practice

3 INTRODUCTION TO PRESS-FIT TECHNOLOGY

3.1 Background of Press-fit Technology Press-fit technology is going back to the 1970s. It was initially used in the telecommunication industry, starting with solid pins and moving later to compliant variants. Press-fit pins with compliant press-fit zones were standardized in the 80s, becoming a standalone IEC standard (IEC 60352-5) in 2004. The press-fit technology was further developed to meet the requirements of high performance/harsh environment (IPC Class 3) electronic products. This finally triggered the preparation of the IPC-9797 Press-fit Standard for Automotive Requirements and Other High Reliability

Applications. Typical fields of application are single-pin insertion as well as the assembly of connectors integrated in housings.

3.2 Press-Fit Technology Press-fit technology establishes an electro-mechanical connection between a compliant press-fit zone and press-fit plated-through hole (PPTH) of a printed board (PB). In the contact areas, between the surfaces of the compliant

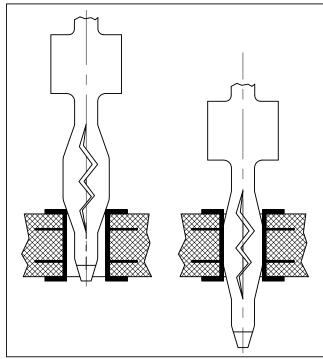


Figure 3-1 Compliant Press-Fit Zone in PPTH

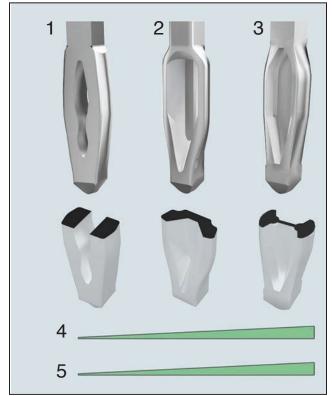


Figure 3-2 Examples of Different Styles of Compliant Press-Fit Zones [1]

- 1. Eye of the Needle
- 2. Spring Shape
- 3. Cracking Zone
- 4. Spring Stiffness5. Plastic Deformation